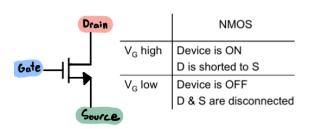
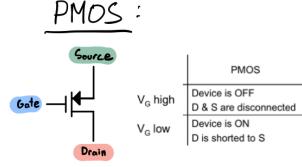
Basic MOS Device Physics:

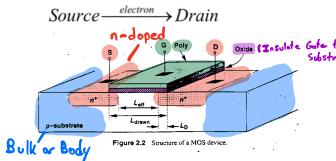
NMOS:



Current flows from Drain to Source



Current flows from Source to Drain



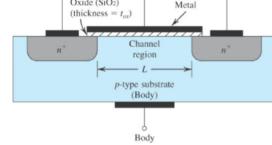
Threshold Voltage:

- The voltage Vth such that the device is OV if VG > Vth

Long-Channel Current:

$$I_0 = N_n C_{ox} \cdot \frac{\forall}{L} \cdot \left[(V_{GS} - V_{Hh}) \cdot V_{DS} - \frac{1}{2} V_{DS}^2 \right]$$

Source \xrightarrow{hole} Drain Source (S) Gate (G) Drain (D) Oxide (SiO2) Metal (thickness = t_{ax}) Channel region n^+



Analytically

$$V_{TH} = \Phi_{MS} + 2 \cdot \left| \Phi_F \right| + \frac{\left| Q_{dep} \right|}{C_{ox}}$$

Where:

- Φ_{MS} = Built in Potential = $\Phi_{gate} \Phi_{Silicon}$
 - = the difference between the work functions of the polysilicon gate and the silicon substrate
- $\Phi_{_F}$ = Work Function (electrostatic potential) = $\frac{K \cdot T}{q} \cdot \ln \left(\frac{N_{_{mb}}}{n_{_i}} \right)$
- $Q_{\mbox{\tiny dep}} = {
 m Charge} \ {
 m in} \ {
 m the} \ {
 m depletion} \ {
 m region} = \ \sqrt{4 \cdot q \cdot arepsilon_{\mbox{\tiny s}\mbox{\tiny l}} \cdot \left| \Phi_{\mbox{\tiny F}} \right| \cdot N_{\mbox{\tiny s}\mbox{\tiny obs}}}$

Regions of Operation:

- Vos & VGs - V+h TRIODE(LINEAR)

Current in Triode Region:

$$I_D = \mu_n \cdot C_{ox} \cdot \frac{W}{L} \cdot \left[\left(V_{GS} - V_{TH} \right) \cdot V_{DS} - \frac{1}{2} \cdot V_{DS}^2 \right]$$

Effective Voltage:

Veff = VGs - Vth

* Sometimes called Overdrive Voltage

$$\frac{W}{L}$$
 = Aspect Rotio

- Small Vos, Voszzz (VGS-V+h) DEEP TRIODE

The device will behave like a variable resistor

$$I_D = \mu_n \cdot C_{ox} \cdot \frac{W}{L} \cdot (V_{GS} - V_{TH}) \cdot V_{DS}$$

$$R_{ON} = \frac{V_{DS}}{I_D} = \frac{1}{\mu_n \cdot C_{ox} \cdot \frac{W}{I} \cdot (V_{GS} - V_{TH})}$$

- VDS > VGS - V+h SATURATION (Active)

channel is pinched off.

$$I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L!} (V_{GS} - V_{TH})^2$$

Summary:

Current Equation for NMOS:

Current Equation for PMOS: